BOND PULL

MIL-STD 883 Method 2011

PURPOSE. The purpose of this test is to measure bond strengths, evaluate bond strength distributions, or determine compliance with specified bond strength requirements of the applicable acquisition document. This test may be applied to the wire-to-die bond, wire-to-substrate bond, or the wire-to-package lead bond inside the package of wire-connected microelectronic devices bonded by soldering, thermocompression, ultrasonic, or related techniques. It may also be applied to bonds external to the device such as those from device terminals-to-substrate or wiring board or to internal bonds between die and substrate in non-wire-bonded device configurations such as beam lead or flip chip devices.

Test Results

Part	Description	Condition	Sample Size	Date	Results
MM1H-0320LCH-2	MMIC Mixer 3 - 20 GHz	-	4	8/29/18	Pass
MM2K-0530LCH-2	MMIC Mixer 5 - 30 GHz	-	10	4/12/18	Pass
MM1K-1140HCH-2	MMIC Mixer RF 11 - 40 GHz	-	10	2/7/18	Pass
MM1H-0320LCH-2	MMIC Mixer 3 - 20 GHz	-	4	1/25/18	Pass
MM1H-1140HCH-2	MMIC Mixer RF 11 - 40 GHz	-	4	1/12/18	Pass

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